

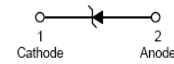
Features

- Planar die construction.
- "A" for $\pm 1\%$ tolerance.
- General purpose, medium current.
- Ideally suited for automated assembly processes.

HF

Mechanical Data

- Case: SOD-123.
- Molding Compound, UL Flammability Classification Rating 94V-0.
- Terminals: Tin Plated Leads, Solderable Per MIL-STD-202, Method 208.



BZT52A7V5
SOD-123

Ordering Information

Part Number	Package	Shipping	Marking Code
BZT52A7V5	SOD-123	3000 pcs / Tape & Reel	A7V5

Maximum Ratings (@ $T_A=25^\circ\text{C}$ unless otherwise specified)

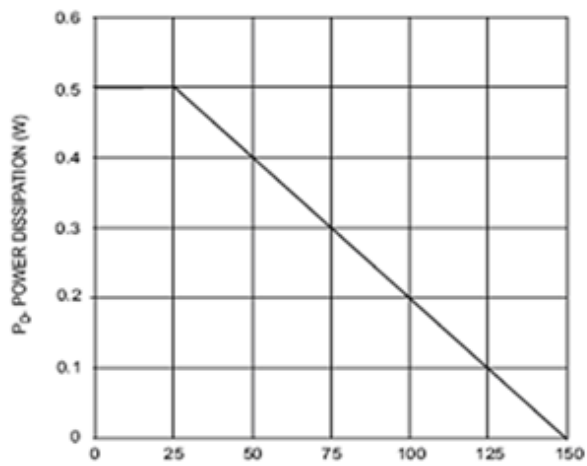
Characteristic	Symbol	Value	Units
Forward Voltage @ $I_F=10\text{mA}$	V_F	0.9	V
Power Dissipation	P_D	500	mW
Typical Thermal Resistance Per Leg ^(Note1)	$R_{\theta JA}$	305	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	180	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-65 to +150	$^\circ\text{C}$

Note 1: Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm².

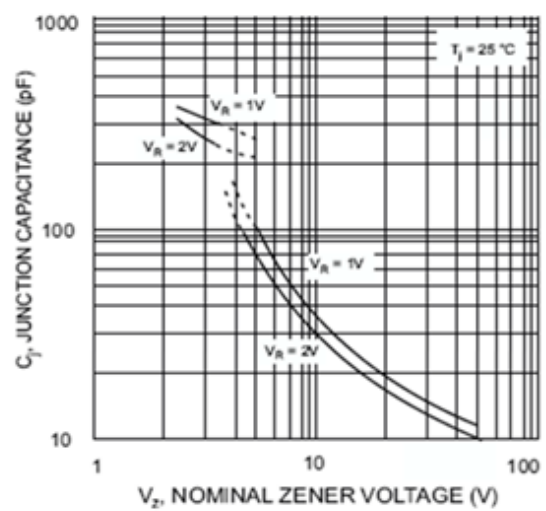
Electrical Characteristics (@ $T_A=25^\circ\text{C}$ unless otherwise specified)

Type Number	V_Z			Z_{ZT}	Z_{ZK}	Maximum Reverse Current		Typical Temperature Coefficient @ I_{ZTC} mV/ $^\circ\text{C}$		Test Current I_{ZTC}
	@ $I_{ZT}=5\text{mA}$			@ $I_{ZT}=5\text{mA}$	@ $I_{ZT}=1\text{mA}$	I_R	V_R			
	Nom(V)	Min(V)	Max(V)	Ω	Ω	μA	V	Min	Max	mA
BZT52A7V5	7.5	7.425	7.575	7	50	0.9	5	2.5	5.3	5

TYPICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified



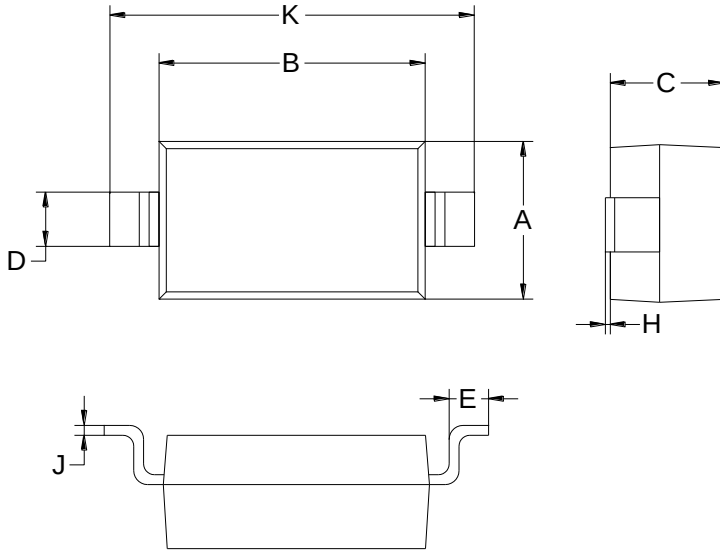
T_A , AMBIENT TEMPERATURE ($^\circ\text{C}$)
 Fig. 1 Power Dissipation vs Ambient Temperature



V_Z , NOMINAL ZENER VOLTAGE (V)
 Fig. 2 Junction Capacitance vs Nominal Zener Voltage

Package Outline Dimensions(unit:mm)

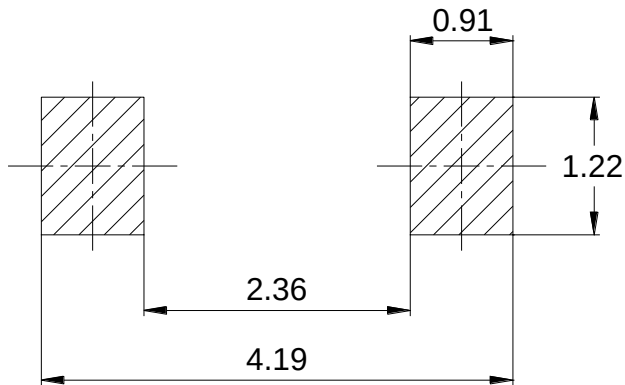
SOD-123



SOD-123		
Dim	Min	Max
A	1.45	1.75
B	2.55	2.85
C	1.00	1.30
D	0.50	0.60
E	0.25	0.45
H	0.02	0.10
J	0.05	0.15
K	3.55	3.85

Mounting Pad Layout(unit:mm)

SOD-123



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